

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application.

**Listing of Claims:**

Claims 1-42 (canceled)

Claims 43-55, 60-62 and 66-69 (canceled)

Claim 56 (previously presented): A biaxially oriented polyester film produced from a polyester comprising:

- (1) diacid residues comprising at least 90 mole percent of terephthalic acid residues, naphthalenedicarboxylic acid residues or combinations thereof; and
- (2) diol residues comprising at least 90 mole percent of 1,4-cyclohexanedimethanol residues,

wherein the polyester film is stretched at a ratio of about 2.5X to 3X in the machine direction (MD) and about 2.5X to 3X in the transverse direction (TD) at stretching temperatures between 90 and 110°C,

wherein the stretched film is subsequently heat-set at an actual film temperature of from 260°C to T<sub>m</sub>, wherein T<sub>m</sub> is the melting point of the polyester as measured by differential scanning calorimetry (DSC), while maintaining the dimensions of the stretched film, and

wherein the biaxially oriented and heat-set polyester film undergoes not more than 3% shrinkage when immersed for 10 seconds in a solder bath preheated to 260°C and exhibits a coefficient of thermal expansion value of 10-85 ppm/°C when measured between 120 and 150°C, and a coefficient of thermal expansion value of 10-42 ppm/°C when measured between 25 and 90°C.

Claim 57 (previously presented): The biaxially oriented polyester film of Claim 56 wherein the polyester has a melting point of at least 270°C and an inherent viscosity of

0.4 to 1.2 as measured at 25°C using 0.50 gram of polymer per 100 mL of a solvent composed of 60 weight percent phenol and 40 weight percent tetrachloroethane according to ASTM method D2857-95, and comprises:

- (1) diacid residues comprising at least 97 mole percent of terephthalic acid residues, naphthalenedicarboxylic acid residues or combinations thereof; and
- (2) diol residues comprising at least 97 mole percent of 1,4-cyclohexanedimethanol residues.

Claim 58 (previously presented): The biaxially oriented polyester film of Claim 56 wherein the polyester film is sequentially stretched in the machine and the transverse directions, and the stretched film is heat-set at an actual film temperature of from 260°C to  $T_m$  for a period of time of 1 to 120 seconds while maintaining the dimensions of the stretched film.

Claim 59 (previously presented): The biaxially oriented polyester film of Claim 56 wherein the polyester film is simultaneously stretched in the machine and the transverse directions, and the stretched film is heat-set at an actual film temperature of from 260°C to  $T_m$  for a period of time of 1 to 120 seconds while maintaining the dimensions of the stretched film.

Claim 63 (previously presented): A thermoplastic article comprising one or more laminates, wherein at least one of said laminates comprises in order:

- I. a thermally curable adhesive; and
- II. a biaxially oriented and heat-set polyester film produced from a polyester comprising:
  - (1) diacid residues comprising at least 90 mole percent of terephthalic acid residues, naphthalenedicarboxylic acid residues or combinations thereof; and
  - (2) diol residues comprising at least 90 mole percent of 1,4-cyclohexanedimethanol residues,

wherein said polyester film is stretched at a ratio of about 2.5X to 3X in the machine direction (MD) and about 2.5X to 3X in the transverse direction (TD) at stretching temperatures between 90 and 110°C,

wherein the stretched film is subsequently heat-set at an actual film temperature of from 260°C to  $T_m$ , wherein  $T_m$  is the melting point of the polymer as measured by differential scanning calorimetry (DSC), while maintaining the dimensions of the stretched film, and

wherein the biaxially oriented and heat-set polyester film undergoes not more than 3% shrinkage when immersed for 10 seconds in a solder bath preheated to 260°C and exhibits a coefficient of thermal expansion value of 10-85 ppm/°C when measured between 120 and 150°C, and a coefficient of thermal expansion value of 10-42 ppm/°C when measured between 25 and 90°C.

Claim 64 (previously presented): The thermoplastic article of Claim 63 wherein said at least one laminate comprises in order:

- I. a copper layer;
- II. said thermally curable adhesive; and
- III. said biaxially oriented and heat-set polyester film.

Claim 65 (previously presented): The thermoplastic article of Claim 64 wherein the copper layer has a thickness of 17 to 140 microns; and the polyester has a melting point of at least 270°C and an inherent viscosity of 0.4 to 1.2 as measured at 25°C using 0.50 gram of polymer per 100 mL of a solvent composed of 60 weight percent phenol and 40 weight percent tetrachloroethane according to ASTM method D2857-95, and comprises:

- (1) diacid residues comprising at least 97 mole percent of terephthalic acid residues, naphthalenedicarboxylic acid residues or combinations thereof; and
- (2) diol residues comprising at least 97 mole percent of 1,4-cyclohexanedimethanol residues.

Claim 70 (previously presented): A flexible electronic circuit board comprising at least one biaxially oriented polyester film produced from a polyester comprising:

- (1) diacid residues comprising at least 90 mole percent of terephthalic acid residues, naphthalenedicarboxylic acid residues or combinations thereof; and
- (2) diol residues comprising at least 90 mole percent of 1,4-cyclohexanedimethanol residues,

wherein the polyester film is stretched at a ratio of about 2.5X to 3X in the machine direction (MD) and about 2.5X to 3X in the transverse direction (TD) at stretching temperatures between 90 and 110°C,

wherein the stretched film is heat-set at an actual film temperature of from 260°C to  $T_m$ , wherein  $T_m$  is the melting point of the polyester as measured by differential scanning calorimetry (DSC), while maintaining the dimensions of the stretched film, and

wherein the biaxially oriented and heat-set polyester film undergoes not more than 3% shrinkage when immersed for 10 seconds in a solder bath preheated to 260°C and exhibits a coefficient of thermal expansion value of 10-85 ppm/°C when measured between 120 and 150°C, and a coefficient of thermal expansion value of 10-42 ppm/°C when measured between 25 and 90°C.

Claim 71 (previously presented): The flexible electronic circuit board of Claim 70 wherein said polyester has a melting point of at least 270°C and an inherent viscosity of 0.4 to 1.2 as measured at 25°C using 0.50 gram of polymer per 100 mL of a solvent composed of 60 weight percent phenol and 40 weight percent tetrachloroethane according to ASTM method D2857-95, and comprises:

- (1) diacid residues comprising at least 97 mole percent of terephthalic acid residues, naphthalenedicarboxylic acid residues or combinations thereof; and
- (2) diol residues comprising at least 97 mole percent of 1,4-cyclohexanedimethanol residues.

Claim 72 (previously presented): The flexible electronic circuit board of Claim 70 comprising one or more laminates, wherein at least one of said laminates comprises in order:

71562 US 02

- I. a copper layer;
- II. a thermally curable adhesive; and
- III. said biaxially oriented and heat-set polyester film.